

China Semiconductor Technology International Conference (CSTIC) 2018 Report

March 11-12, 2018

Shanghai, China



CONNECT



**SEMICON
CHINA**

FPDCHINA

semi

Plenary Keynote Speakers



Prof. Chenming Hu
FinFET Inventor
Microelectronic Scientist



Dr. Kevin Zhang
Vice President
Business Development
TSMC



Dr. PR (Chidi) Chidambaram
Vice President
QCT Process Technology &
Foundry Engineering
Qualcomm



Dr. Zhiyong Ma
Vice President
Technology &
Manufacturing Group
Intel

CSTIC 2018 Organizers 2018

Organizer:



Co-organizer:



Co-sponsor:



Proceedings Publication:



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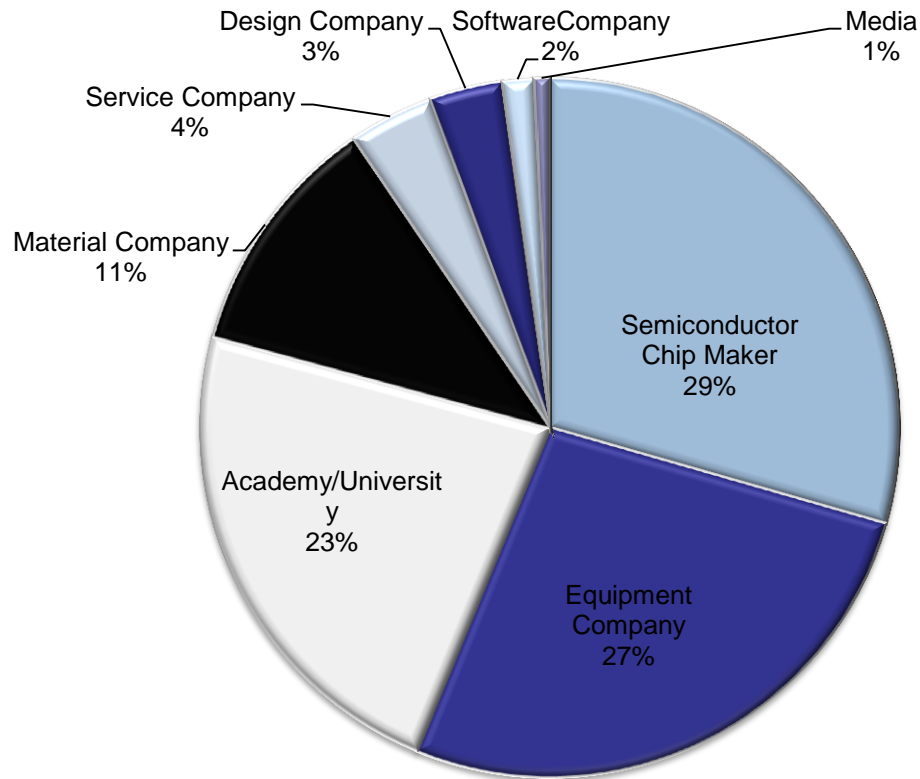
Attendee Numbers



CSTIC 2018	Attendee Number
Conference	684
Plenary Session	549
Symposium I: Device Engineering and Memory Technology	287
Symposium II: Lithography and Patterning	318
Symposium III: Dry & Wet Etch and Cleaning	206
Symposium IV: Thin Film, Plating and Process Integration	172
Symposium V: CMP and Post-Polish Cleaning	178
Symposium VI: Metrology, Reliability and Testing	110
Symposium VII: Packaging and Assembly	175
Symposium VIII: MEMS, Sensors and Emerging Semiconductor Technologies	89
Symposium IX: Design and Automation of Circuits and Systems	86
Symp II & III Joint Session	239
Panel Discussion: What are the yield killers and the solutions of 14nm to 7nm node technologies?	239

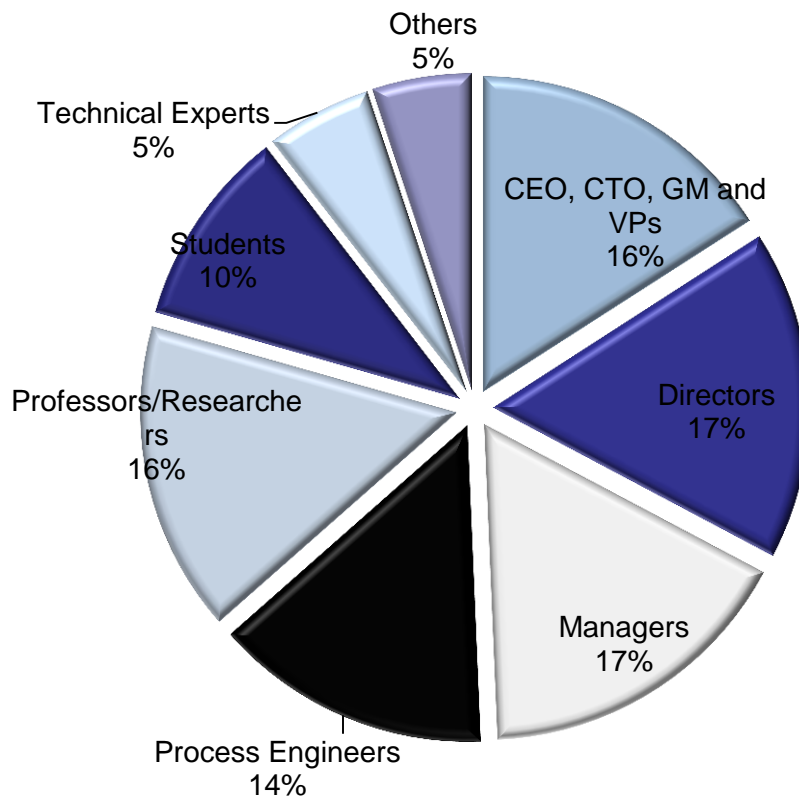
**Symposium I-IX attendee number is Day 1 and Day 2 in total*

Attendee Industry Distribution



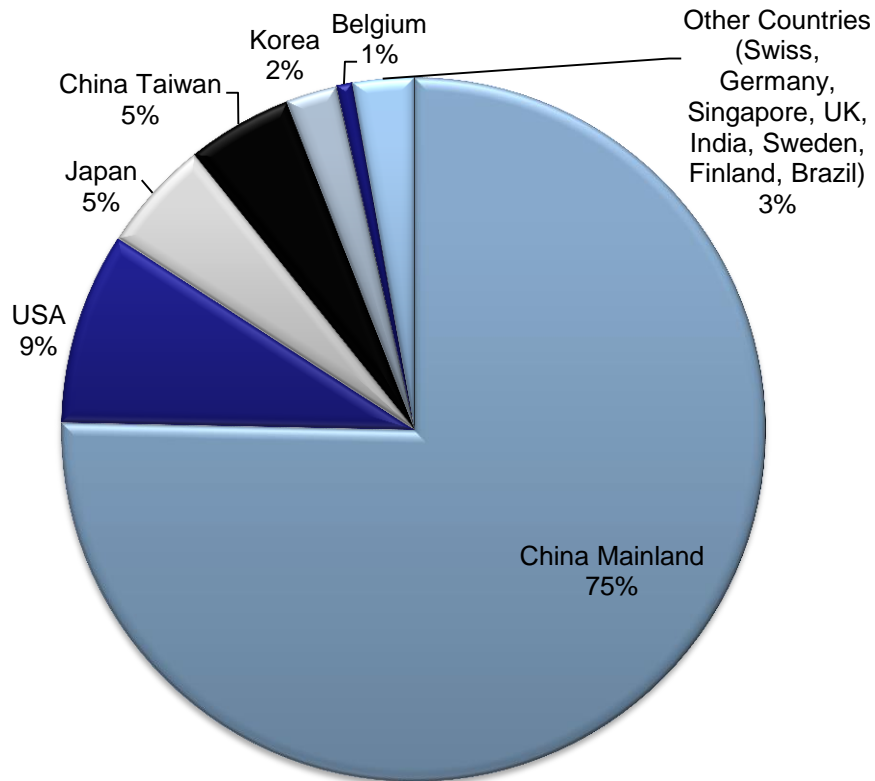
- 76% attendees from industry
- 23% attendees from academy
- Chip companies like SMIC, HLMC, H-Grace, Intel, IBM, TSMC, UMC, Global Foundry, Samsung, Micron, JCET, ASE, Amkor, Hua Tian, Infineon and etc. joined the conference

Attendee's Job Titles



- 33% of our attendees are directors or above, who are the decision makers in companies.

Attendee Country Distribution



- Speakers and attendees are from 14 different countries
- More than 150 speakers and attendees are overseas industry leaders or experts

2019 Conference Chair and Co- Chairs 2018



Dr. Ru Huang
Chair
Peking University, China



Dr. Qinghuang Lin
Executive Co-Chair
IBM, USA



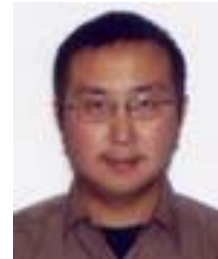
Dr. Steve X. Liang
Executive Co-Chair
JCET, China



Dr. Cor Claeys
Co-Chair
KU Leuven, Belgium



Dr. Peilin Song
Co-Chair Publicity
IBM, USA



Dr. Zhen Guo
Co-Chair
Intel, USA



Dr. Hanming Wu
Co-Chair
SMIC, China

CSTIC 2019 Symposium



Symposium I: Device Engineering and Memory Technology

Symposium II: Lithography and Patterning

Symposium III: Dry & Wet Etch and Cleaning

Symposium IV: Thin Film, Plating and Process Integration

Symposium V: CMP and Post-Polish Cleaning

Symposium VI: Metrology, Reliability and Testing

Symposium VII: Packaging and Assembly

Symposium VIII: MEMS, Sensors and Emerging Semiconductor Technologies

Symposium IX: Design and Automation of Circuits and Systems

CSTIC 2019 Plan



- CSTIC 2019 will be held on Mar 18-19, 2019 in Shanghai, in conjunction with SEMICON China
- CSTIC 2019 call for papers and manuscript deadlines
 - Call for paper online: Jun. 30, 2018
 - Abstract deadline: Sep. 30, 2018
 - Acceptance notification: Oct. 15, 2018
 - Manuscript deadline: Dec. 26, 2018

Thank you and see you at
CSTIC 2019



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